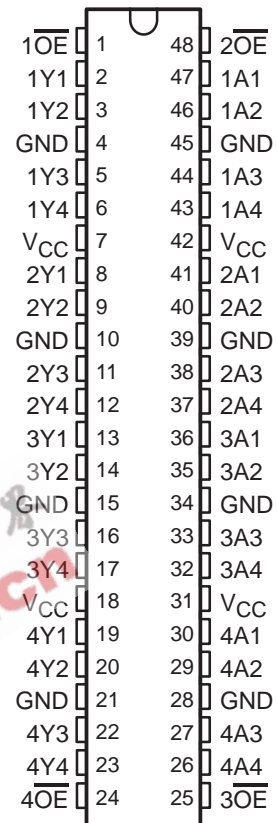


SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCES074E – JUNE 1996 - REVISED JANUARY 1999

- State-of-the-Art Advanced BiCMOS Technology (ABT) *Widebus*™ Design for 2.5-V and 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Power Off Disables Outputs, Permitting Live Insertion
- High-Impedance State During Power Up and Power Down Prevents Driver Conflict
- Uses Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Output Ports Have Equivalent 30- Ω Series Resistors, So No External Resistors Are Required
- Auto3-State Eliminates Bus Current Loading When Output Exceeds $V_{CC} + 0.5$ V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model; and Exceeds 1000 V Using Charged-Device Model, Robotic Method
- Flow-Through Architecture Facilitates Printed Circuit Board Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

SN54ALVTH162244 . . . WD PACKAGE
SN74ALVTH162244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NOTE: For order entry:
The DGG package is abbreviated to G, and
the DGV package is abbreviated to V.

description

The 'ALVTH162244 devices are 16-bit buffers/line drivers designed for low-voltage 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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SN54ALVTH162244, SN74ALVTH162244

2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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description (continued)

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

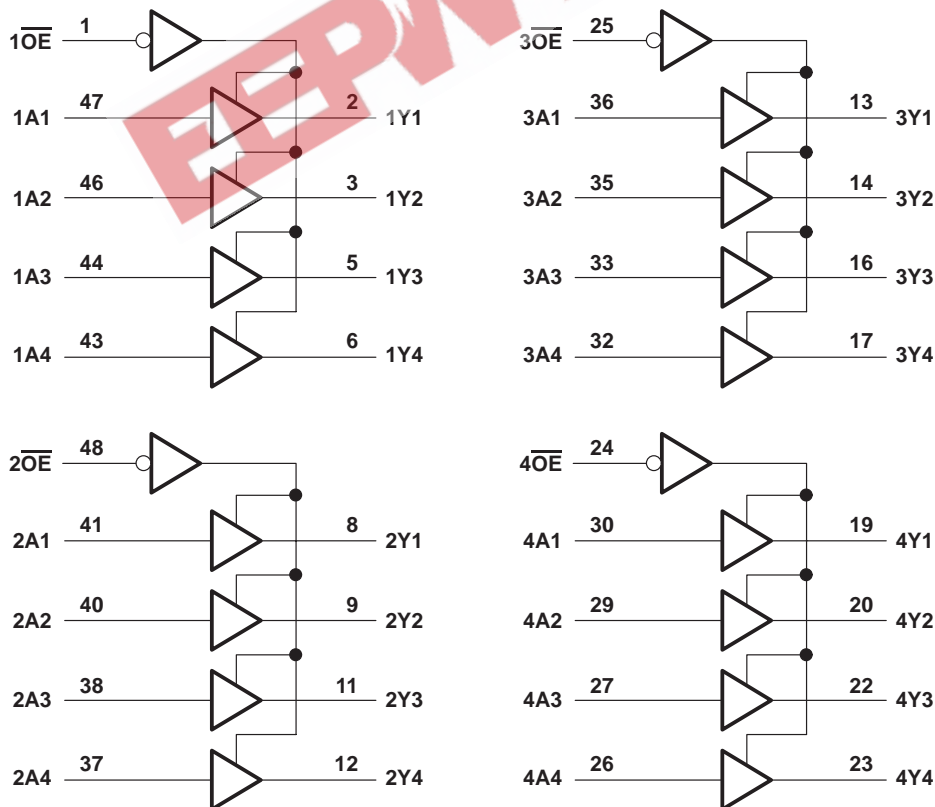
All outputs are designed to sink up to 12 mA and include equivalent 30- Ω resistors to reduce overshoot and undershoot.

The SN54ALVTH162244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALVTH162244 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to 7 V
Output current in the low state, I_{OL}	30 mA
Output current in the high state, I_{OH}	–30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (see Note 3)

		SN54ALVTH162244			SN74ALVTH162244			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	2.3		2.7	2.3		2.7	V
V_{IH}	High-level input voltage	1.7			1.7			V
V_{IL}	Low-level input voltage			0.7			0.7	V
V_I	Input voltage	0	V_{CC}	5.5	0	V_{CC}	5.5	V
I_{OH}	High-level output current			–6			–8	mA
I_{OL}	Low-level output current			8			12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200			200			μs/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

recommended operating conditions, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (see Note 3)

		SN54ALVTH162244			SN74ALVTH162244			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	3		3.6	3		3.6	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0	V_{CC}	5.5	0	V_{CC}	5.5	V
I_{OH}	High-level output current			–8			–12	mA
I_{OL}	Low-level output current			8			12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200			200			μs/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54ALVTH162244, SN74ALVTH162244

2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALVTH162244			SN74ALVTH162244			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		$V_{CC} = 2.3 \text{ V}$, $I_I = -18 \text{ mA}$		-1.2			-1.2			V
V_{OH}		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$, $I_{OH} = -100 \mu\text{A}$		$V_{CC}-0.2$			$V_{CC}-0.2$			V
		$V_{CC} = 2.3 \text{ V}$, $I_{OH} = -6 \text{ mA}$		1.7						
		$V_{CC} = 2.3 \text{ V}$, $I_{OH} = -8 \text{ mA}$					1.7			
V_{OL}		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$, $I_{OL} = 100 \mu\text{A}$		0.2			0.2			V
		$V_{CC} = 2.3 \text{ V}$, $I_{OL} = 8 \text{ mA}$		0.7						
		$V_{CC} = 2.3 \text{ V}$, $I_{OL} = 12 \text{ mA}$					0.7			
I_I	Control inputs	$V_{CC} = 2.7 \text{ V}$, $V_I = V_{CC} \text{ or GND}$		± 1			± 1			μA
		$V_{CC} = 0 \text{ or } 2.7 \text{ V}$, $V_I = 5.5 \text{ V}$		10			10			
	Data inputs	$V_{CC} = 2.7 \text{ V}$		$V_I = 5.5 \text{ V}$		10		10		
				$V_I = V_{CC}$		1		1		
				$V_I = 0$		-5		-5		
I_{off}		$V_{CC} = 0$, $V_I \text{ or } V_O = 0 \text{ to } 4.5 \text{ V}$					± 100			
I_{BHL}^\ddagger		$V_{CC} = 2.3 \text{ V}$, $V_I = 0.7 \text{ V}$		115			115			
I_{BHH}^\S		$V_{CC} = 2.3 \text{ V}$, $V_I = 1.7 \text{ V}$		-10			-10			
I_{BHLO}^\P		$V_{CC} = 2.7 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$		300			300			
$I_{BHHO}^\#$		$V_{CC} = 2.7 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$		-300			-300			
I_{EX}^\parallel		$V_{CC} = 2.3 \text{ V}$, $V_O = 5.5 \text{ V}$		125			125			
$I_{OZ(PU/PD)}^\star$		$V_{CC} \leq 1.2 \text{ V}$, $V_O = 0.5 \text{ V to } V_{CC}$, $V_I = \text{GND or } V_{CC}$, $\overline{OE} = \text{don't care}$		± 100			± 100			
I_{OZH}		$V_{CC} = 2.7 \text{ V}$, $V_O = 2.3 \text{ V}$, $V_I = 0.7 \text{ V or } 1.7 \text{ V}$		5			5			
I_{OZL}		$V_{CC} = 2.7 \text{ V}$, $V_O = 0.5 \text{ V}$, $V_I = 0.7 \text{ V or } 1.7 \text{ V}$		-5			-5			
I_{CC}		$V_{CC} = 2.7 \text{ V}$, $I_O = 0$, $V_I = V_{CC} \text{ or GND}$		Outputs high		0.04 0.1		0.04 0.1		mA
				Outputs low		2.3 4.5		2.3 4.5		
				Outputs disabled		0.04 0.1		0.04 0.1		
C_i		$V_{CC} = 2.5 \text{ V}$, $V_I = 2.5 \text{ V or } 0$		3			3			
C_o		$V_{CC} = 2.5 \text{ V}$, $V_O = 2.5 \text{ V or } 0$		6			6			

† All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

§ The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| Current into an output in the high state when $V_O > V_{CC}$

☆ High-impedance state during power up or power down

SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	SN54ALVTH162244			SN74ALVTH162244			UNIT	
			MIN	TYP†	MAX	MIN	TYP†	MAX		
V _{IK}		V _{CC} = 3 V, I _I = -18 mA			-1.2			-1.2	V	
V _{OH}		V _{CC} = 3 V to 3.6 V, I _{OH} = -100 μA	V _{CC} -0.2			V _{CC} -0.2			V	
		V _{CC} = 3 V, I _{OH} = -8 mA	2							
V _{OL}		V _{CC} = 3 V to 3.6 V, I _{OL} = 100 μA				0.2			V	
		V _{CC} = 3 V, I _{OL} = 8 mA				0.8				
		V _{CC} = 3 V, I _{OL} = 12 mA				0.8				
I _I	Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND				±1			μA	
		V _{CC} = 0 or 3.6 V, V _I = 5.5 V				10				
	Data inputs	V _{CC} = 3.6 V, V _I = 5.5 V				10				
		V _{CC} = 3.6 V, V _I = V _{CC}				1				
		V _{CC} = 3.6 V, V _I = 0				-5				
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V				±100			μA	
I _{BHL} ‡		V _{CC} = 3 V, V _I = 0.8 V	75			75			μA	
I _{BHH} §		V _{CC} = 3 V, V _I = 2 V	-75			-75			μA	
I _{BHLO} ¶		V _{CC} = 3.6 V, V _I = 0 to V _{CC}	500			500			μA	
I _{BHHO} #		V _{CC} = 3.6 V, V _I = 0 to V _{CC}	-500			-500			μA	
I _{EX}		V _{CC} = 3 V, V _O = 5.5 V				125			μA	
I _{OZ(PU/PD)} ★		V _{CC} ≤ 1.2 V, V _O = 0.5 V to V _{CC} , V _I = GND or V _{CC} , \overline{OE} = don't care				±100			μA	
I _{OZH}		V _{CC} = 3.6 V, V _O = 3 V, V _I = 0.8 V or 2 V				5			μA	
I _{OZL}		V _{CC} = 3.6 V, V _O = 0.5 V, V _I = 0.8 V or 2 V				-5			μA	
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		0.07	0.1	0.07		0.1	mA
		Outputs low		3.2	5	3.2		5		
		Outputs disabled		0.07	0.1	0.07		0.1		
ΔI _{CC} □		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND				0.4			mA	
C _i		V _{CC} = 3.3 V, V _I = 3.3 V or 0				3			pF	
C _o		V _{CC} = 3.3 V, V _O = 3.3 V or 0				6			pF	

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

§ The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| Current into an output in the high state when V_O > V_{CC}

★ High-impedance state during power up or power down

□ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ALVTH162244, SN74ALVTH162244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$,
 $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH162244		SN74ALVTH162244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	4.3	1	4.2	ns
t_{PHL}			1.4	3.8	1.5	3.7	
t_{PZH}	OE	Y	1.3	6.9	1.4	6.8	ns
t_{PZL}			1.3	5.2	1.4	5.1	
t_{PHZ}	\overline{OE}	Y	1	4.7	1	4.6	ns
t_{PLZ}			1	3.6	1	3.5	

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$,
 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 2)

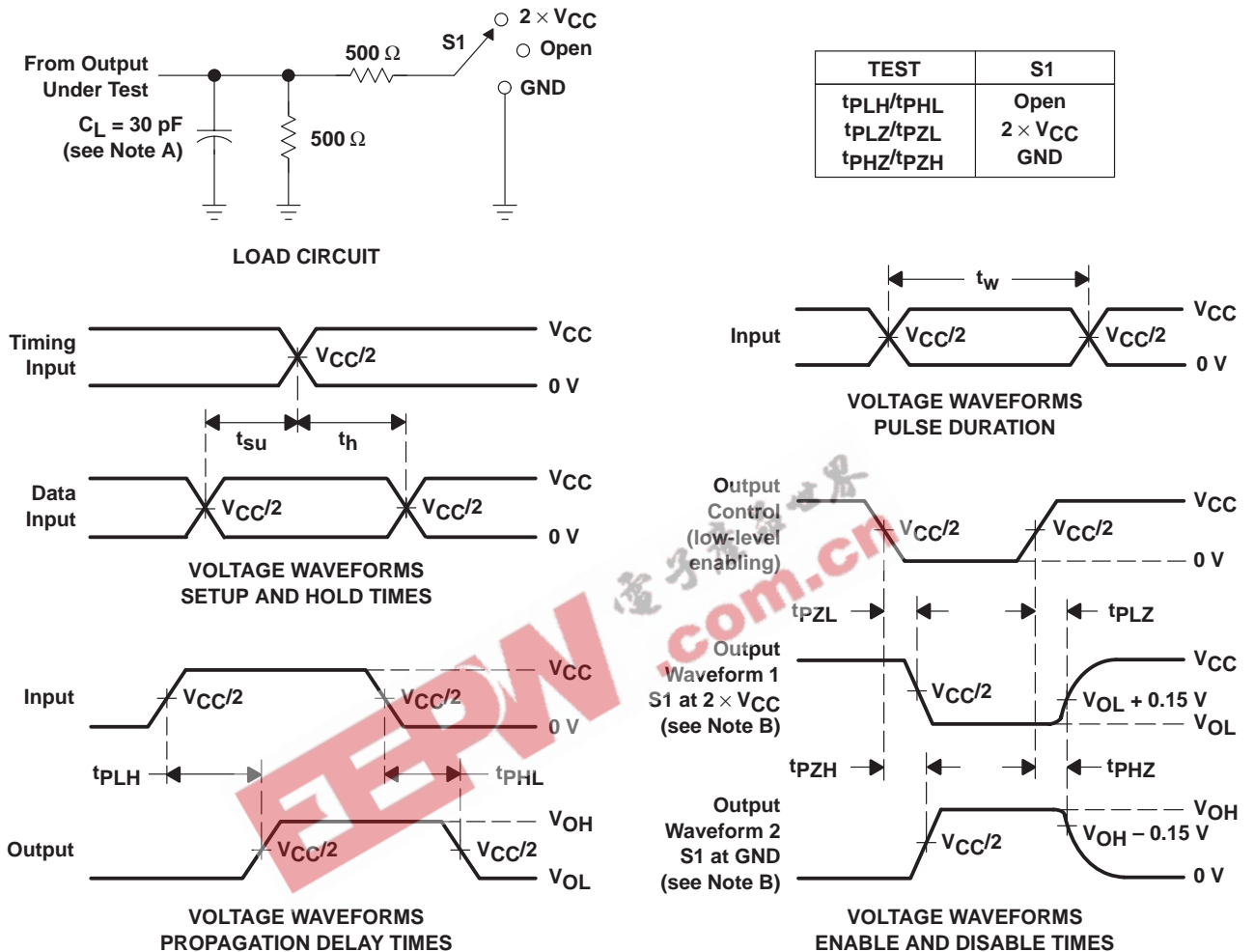
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH162244		SN74ALVTH162244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3.4	1	3.3	ns
t_{PHL}			1	3.4	1	3.3	
t_{PZH}	\overline{OE}	Y	1.4	5	1.5	4.9	ns
t_{PZL}			1.3	3.4	1.4	3.3	
t_{PHZ}	\overline{OE}	Y	1.4	5	1.5	4.9	ns
t_{PLZ}			1.4	4.4	1.5	4.3	

SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

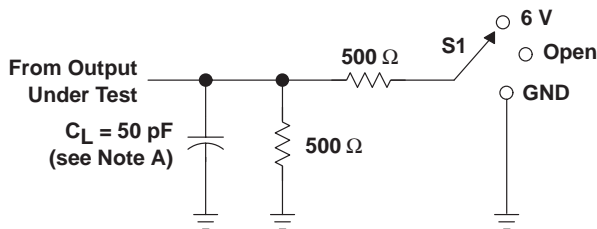
Figure 1. Load Circuit and Voltage Waveforms

SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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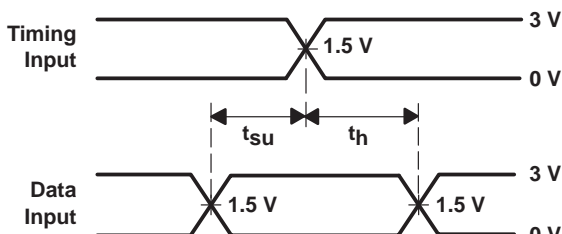
PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$

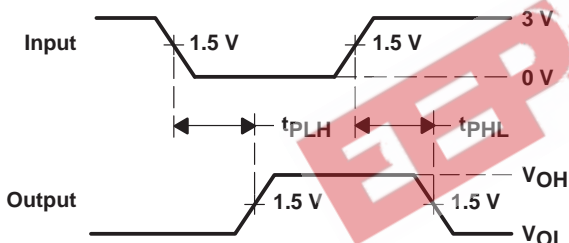


LOAD CIRCUIT

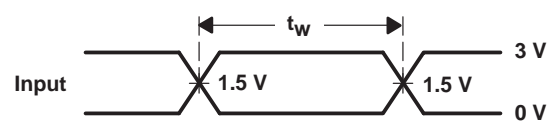
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



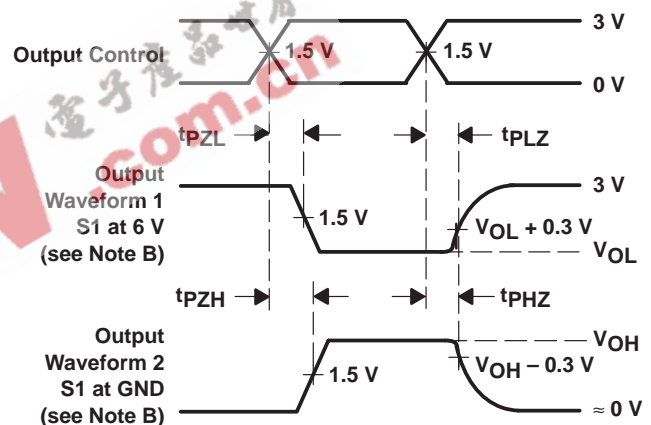
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVTH162244DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244LRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

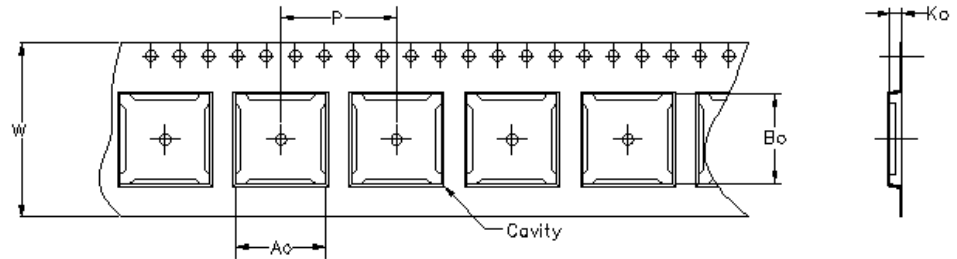
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

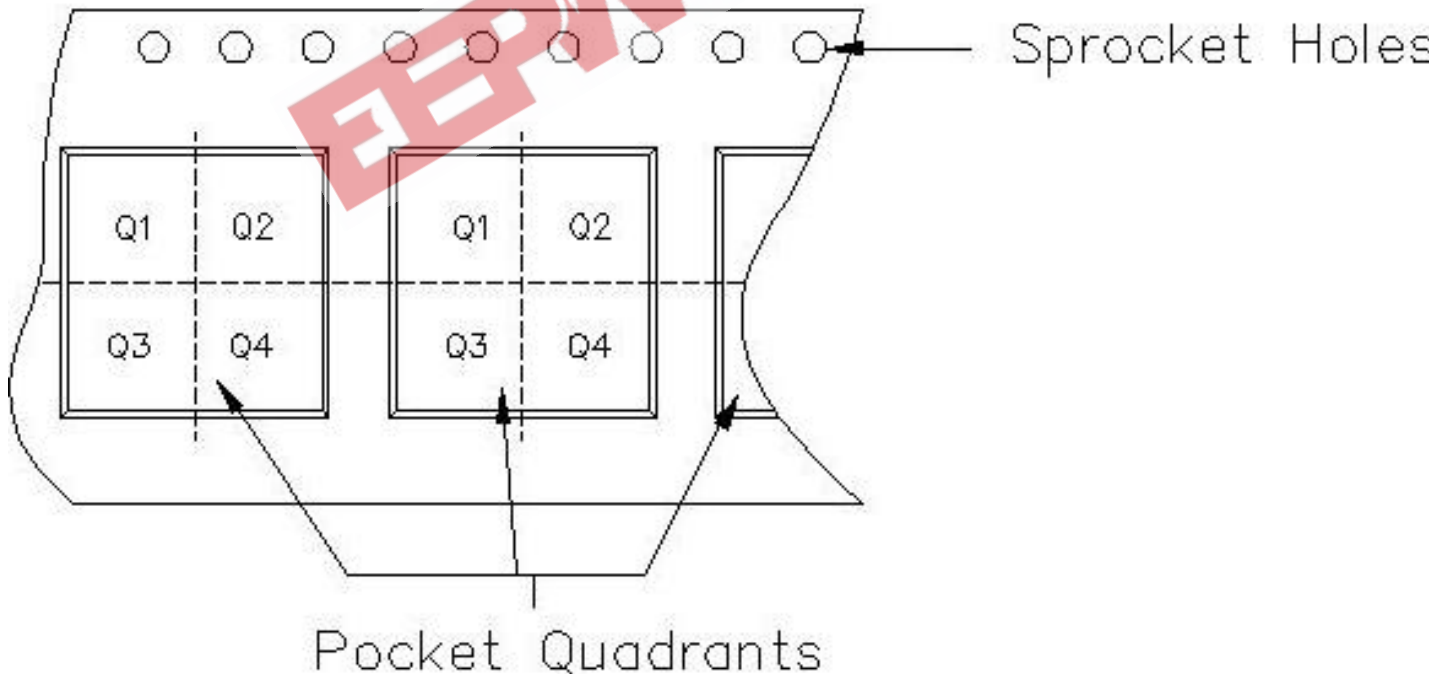
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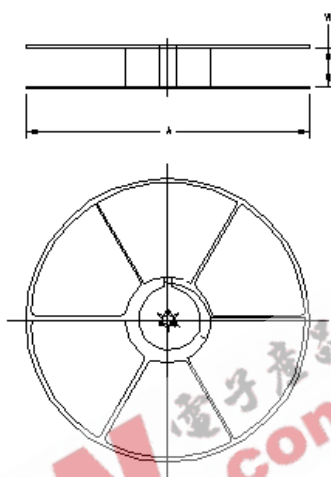
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



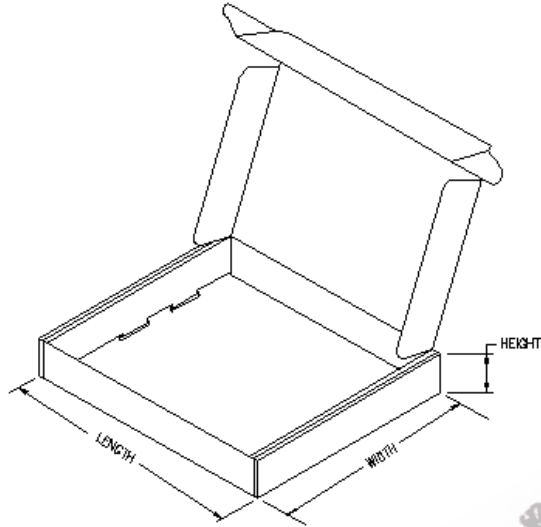
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVTH162244GR	DGG	48	MLA	330	24	8.6	15.8	1.8	12	24	Q1
SN74ALVTH162244LR	DL	48	MLA	330	32	11.35	16.2	3.1	16	32	Q1
SN74ALVTH162244VR	DGV	48	MLA	330	24	6.8	10.1	1.6	12	24	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74ALVTH162244GR	DGG	48	MLA	333.2	333.2	31.75
SN74ALVTH162244LR	DL	48	MLA	336.6	342.9	41.3
SN74ALVTH162244VR	DGV	48	MLA	333.2	333.2	31.75



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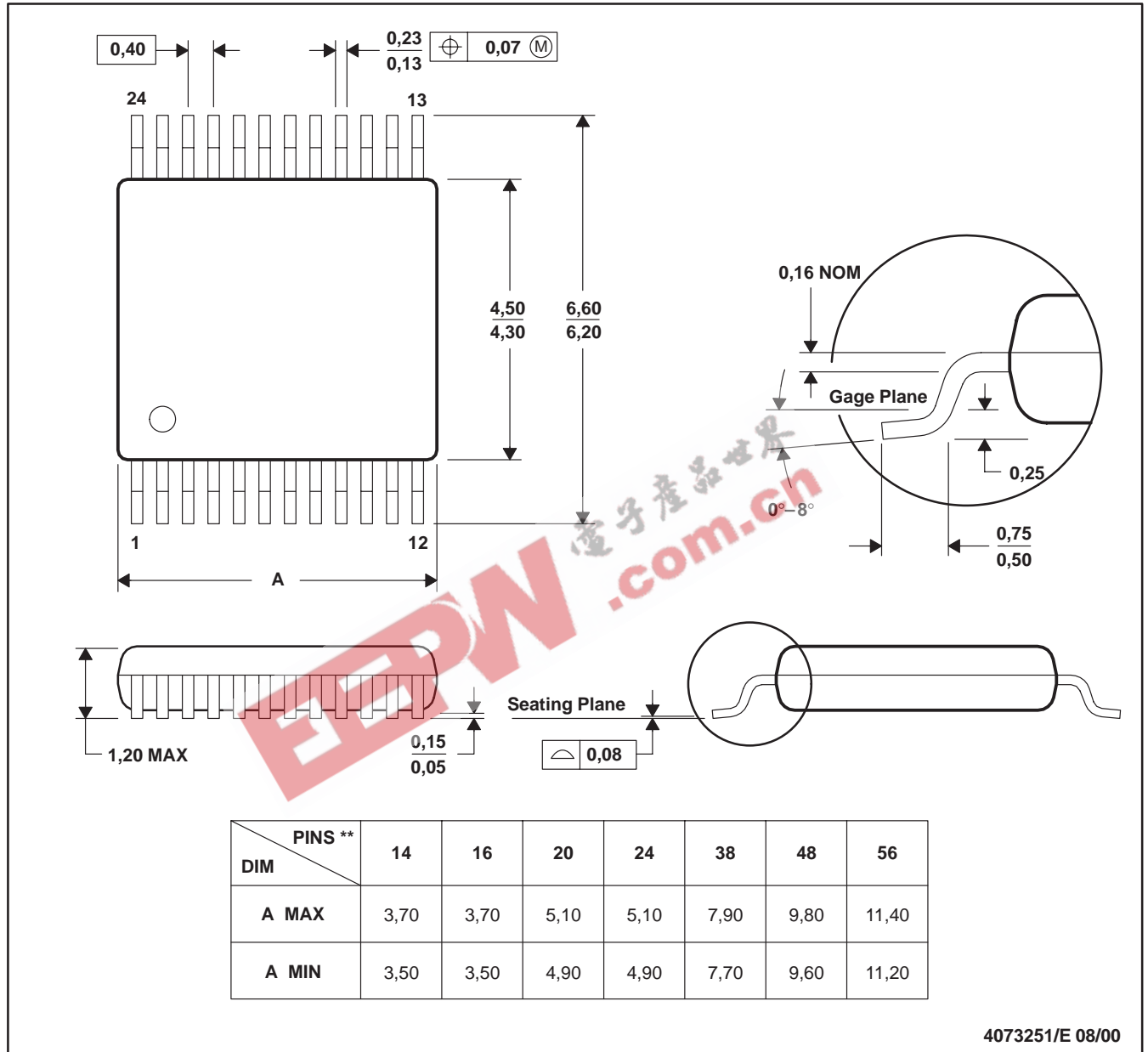
MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

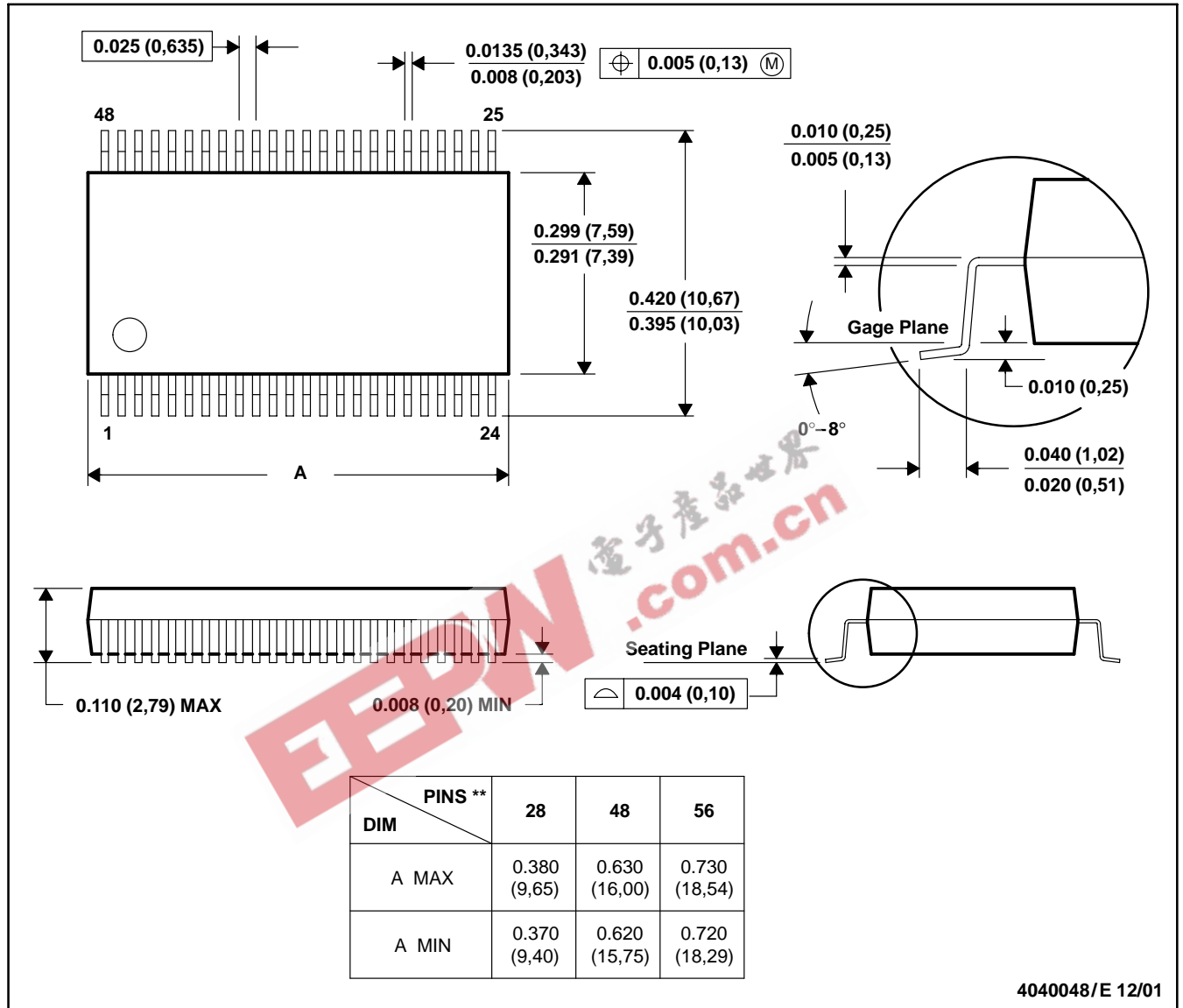
MECHANICAL DATA

MSS0001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

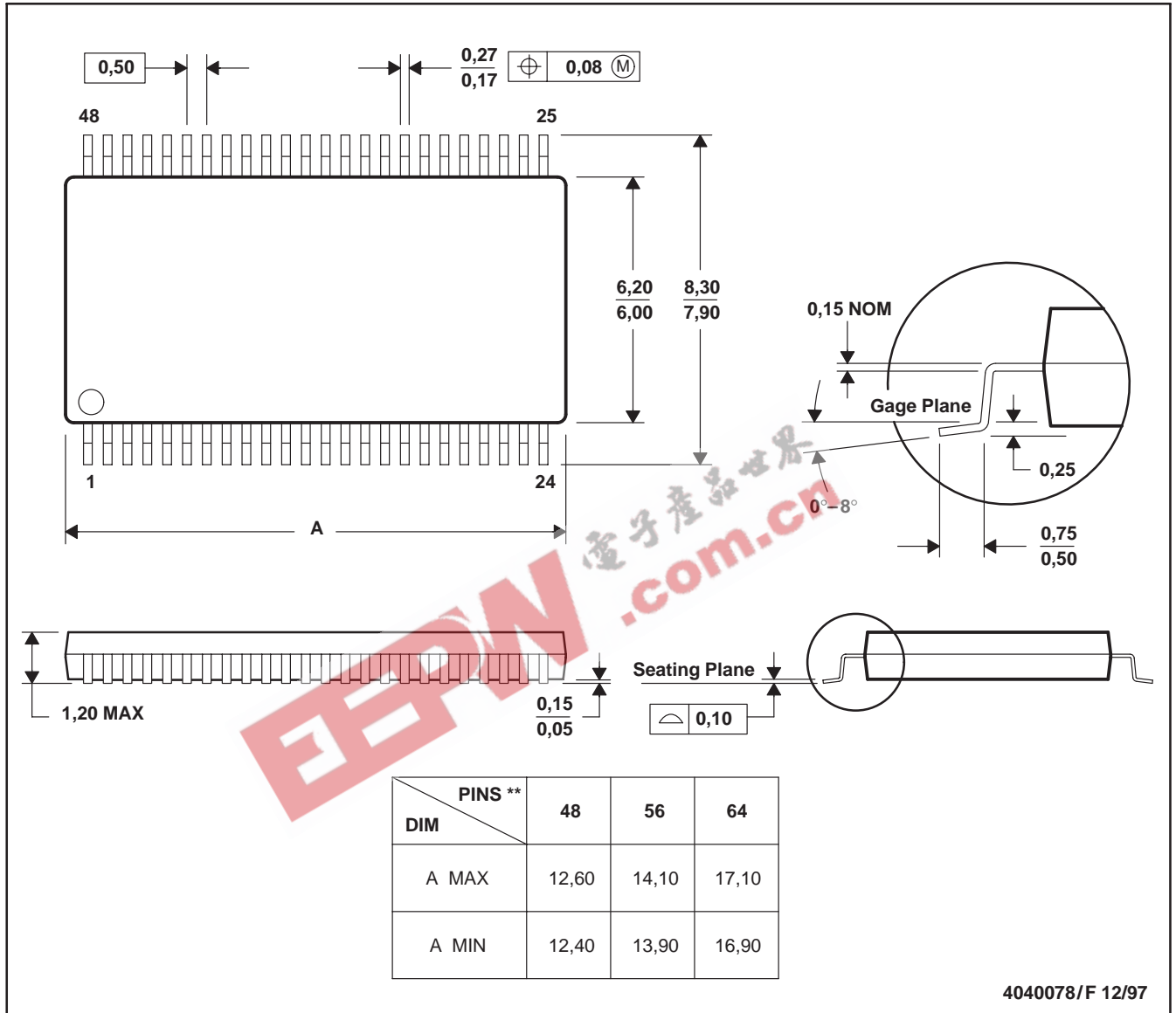
MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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